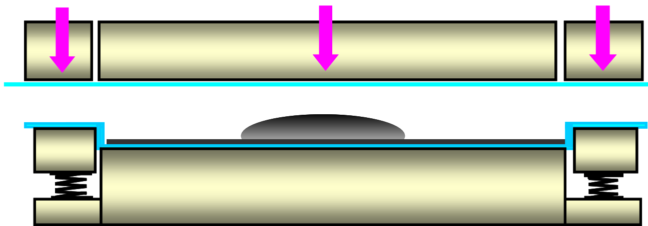
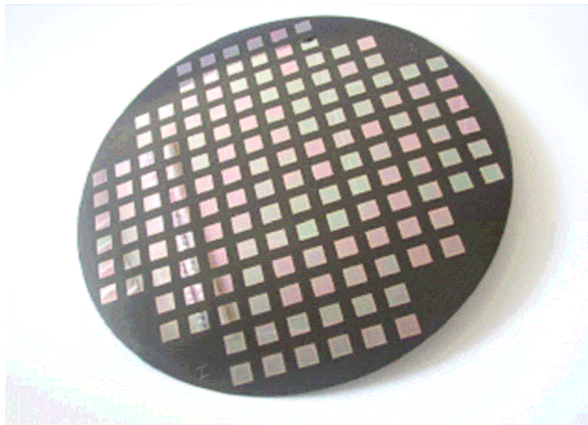
■Liquid Molding Compound T693/R4000 series

Designed for compression mold
Liquid at ambient for dispense application
Good flowability for wide and thin encapsulation
Low stress technology for low warpage

	R4212	R4212-2	R4600-2C80	R4502-T2
Feature	Low warpage	Low warpage	Good dispensability Good adhesion	Low warpage
Application	Embedded WLP	Embedded WLP	PoP, Stacked SiP	Electronic parts
In-Mold Cure	120C/10min	120C/10min	165C/1.5min	150C/3min
Post Mold Cure	150C/1hr	150C/1hr	165C/1hr	150C/1hr
Tg (C, DMA)	160	160	155	170
Flammability	V-0	V-0	HB (Corresponding)	HB (Corresponding)
Cl- Content (ppm)	<20	<20	<20	<20
Na+ Content (ppm)	<10	<10	<10	<10
Storage	Below -40C	Below -40C	Below -40C	Below -40C



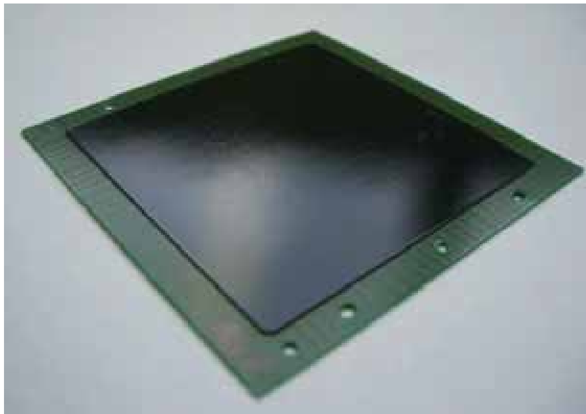
Typical compresion mold method



8 inch embedded WLP with R4212

Reference:

E. Fuergut et al., "An Embedded Device Technology Based on a Molded Reconfigured Wafer"
2006 Electronic Components and Technology Conference



MAP encapsulation on FR4 with R4502-T2